

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
250°C/10 seconds at terminals

Mechanical Data

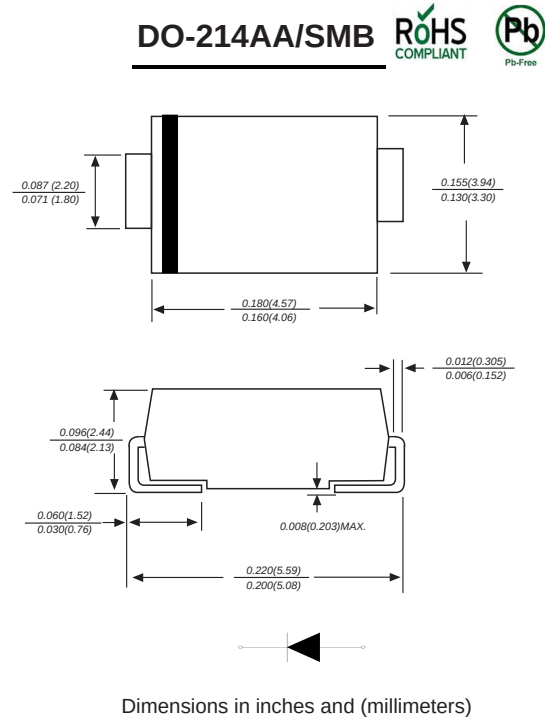
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0035 ounce, 0.098 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS32	SS34	SS36	SS38	SS310	SS315	SS320	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	105	140	V
Maximum DC blocking voltage	V _{DC}	20	40	60	80	100	150	200	V
Maximum average forward rectified current at T _L =100°C	I _(AV)	3.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	100.0							A
Maximum instantaneous forward voltage at 3.0A	V _F	0.50		0.70	0.85		0.95		V
Maximum DC reverse current at rated DC blocking voltage	I _R	0.5 50			0.05 10				mA
Typical thermal resistance	R _{qJA}	85.0							°C/W
Operating junction temperature range	T _J	-55 to +150							°C
Storage temperature range	T _{STG}	-55 to +150							°C

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

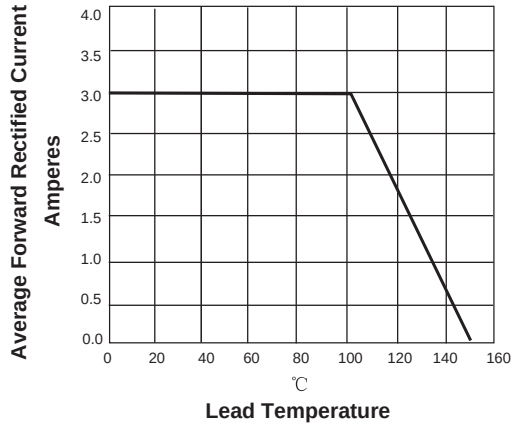


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

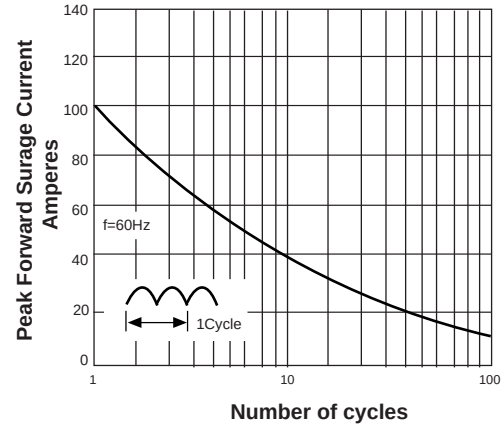


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

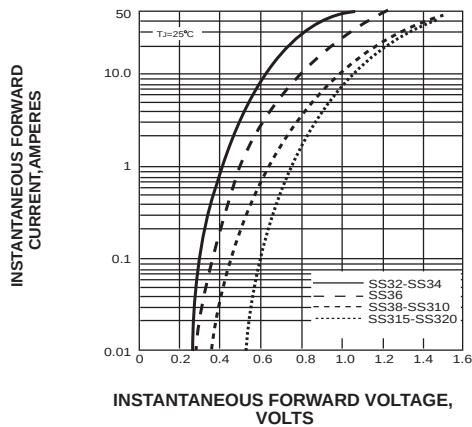
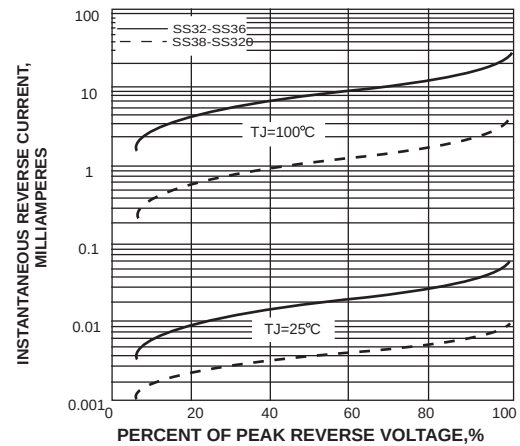
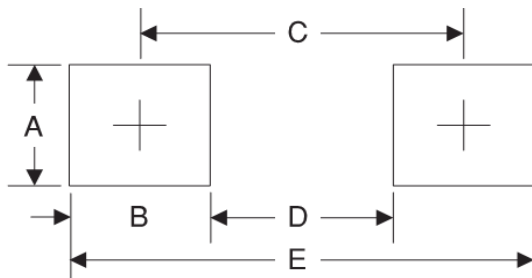


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

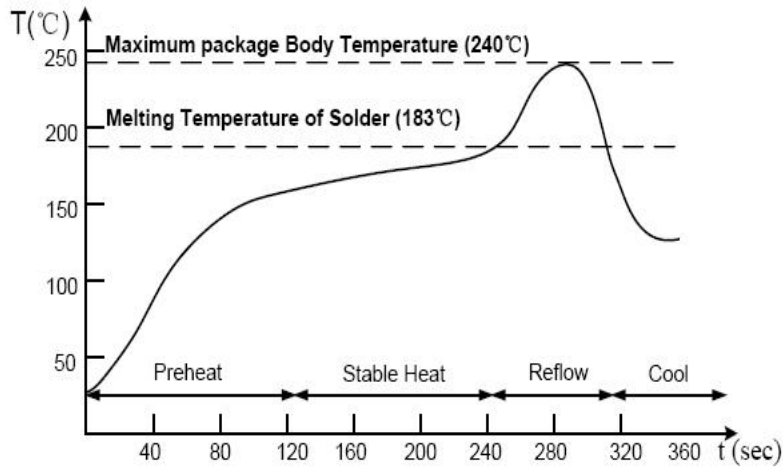


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.30	0.091
B	2.00	0.078
C	4.10	0.161
D	2.10	0.083
E	6.10	0.240

Suggested Soldering Temperature Profile

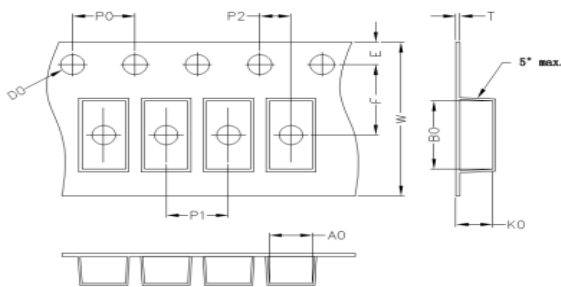


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
3.80	5.40	2.45	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMB	13'	330	3.0	340	6.0	360*360*360	48